

AMENDMENTS TO THE SPECIFICATION

Please change the title to "Method For Fabricating Semiconductor Components Having Conductors With Wire Bondable Metalization Layers".

On page 2, line 1 in the "Cross Reference To Related Applications" added by the Preliminary Amendment dated July 10, 2003, please make the following addition.

Cross Reference To Related Applications

This application is a division of serial no. 10/183,705, filed 06/25/2002, Patent No. 6,784,544 B1.